



—Ion migration suppression on fine pattern—

Coverlay "CG series"

Example of use

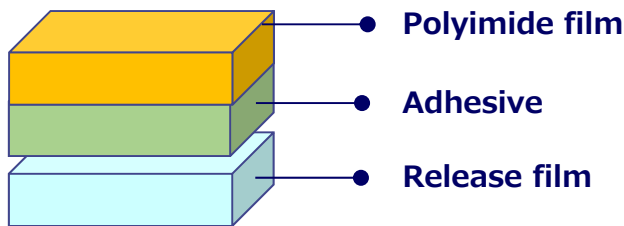
- Smartphone
- Tablet PC
- Laptop computer



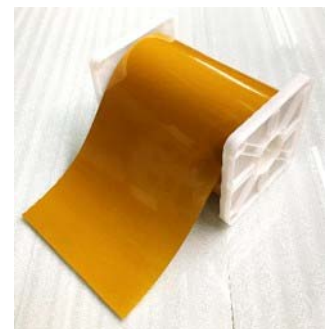
Characteristics

- High performance in insulation resistance on fine pattern.
- Good workability by quick-press.

Product structure



Appearance

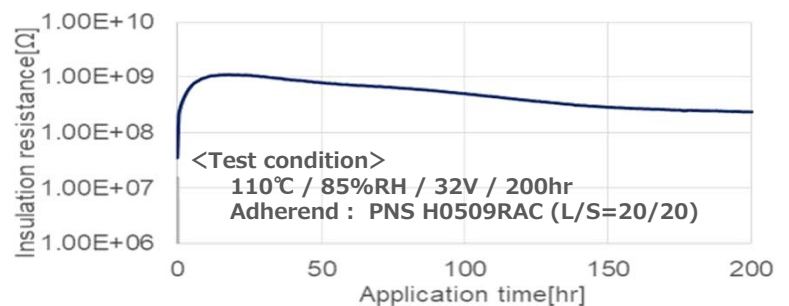


Product Properties

Item	Unit	CG
90° Peel strength (Cu peeling)	N/cm	8
Solder heat resistance	°C	300
UL94 Flammability	—	V-0
bHAST	—	> 200hr
Tg (Adhesive only)	°C	63
Elastic modulus (Adhesive only)	GPa	1.7

Sample making condition : 160°C×3MPa×60min

<bHAST>



<Workability by quick-press>

		Temperature (°C)		
		165	175	185
Application time (Sec.)	30	NG	OK	OK
	60	OK	OK	OK
	90	OK	OK	OK

CVL : Arisawa "CGHB 1215" (PI : 12.5μm, Ad : 15μm)
 FCCL : Arisawa "PNS H1012RAH" (L/S=100/100μm)
 Quick-press conditions : 165-185°C/3MPa/pre-heating for 10sec. /30-90sec.



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The data in this document are measured values, not for guaranteed.